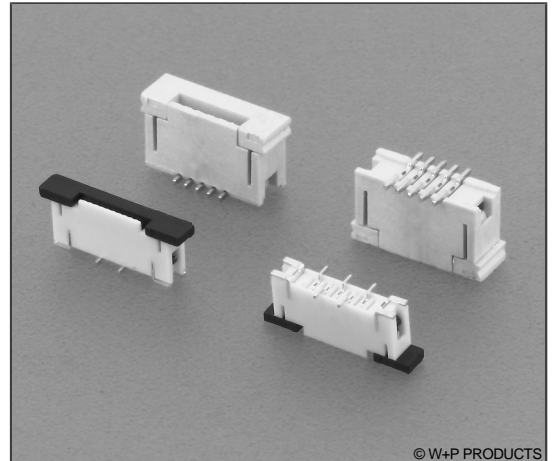


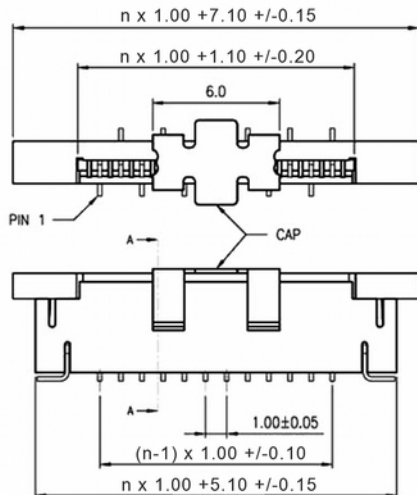
Technische Daten / Technical Data

Isolierkörper <i>Insulator</i>	Thermoplastischer Kunststoff, nach UL94 V-0 <i>Thermoplastic, rated UL94 V-0</i>
Kontaktmaterial <i>Contact Material</i>	Kupferlegierung <i>Copper alloy</i>
Kontaktfläche <i>Contact Surface</i>	Verzinkt <i>Tin plated</i>
Durchgangswiderstand <i>Contact Resistance</i>	< 20mΩ
Isolationswiderstand <i>Insulation Resistance</i>	> 50MΩ
Spannungsfestigkeit <i>Test Voltage</i>	250V _{AC}
Nennspannung <i>Voltage Rating</i>	50V _{DC}
Nennstrom <i>Current Rating</i>	0,5A
Temperaturbereich <i>Temperature Range</i>	-20°C ... +85°C
Verarbeitung <i>Processing</i>	Reflow-Lötverfahren <i>Reflow soldering</i>

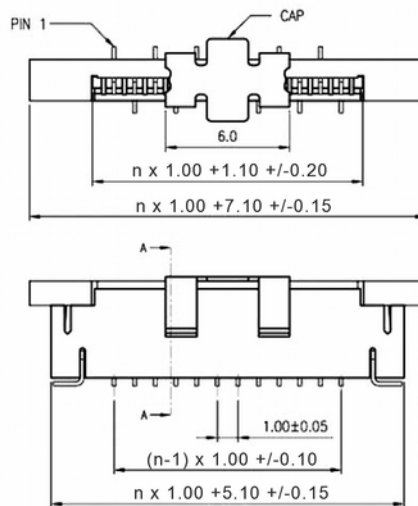


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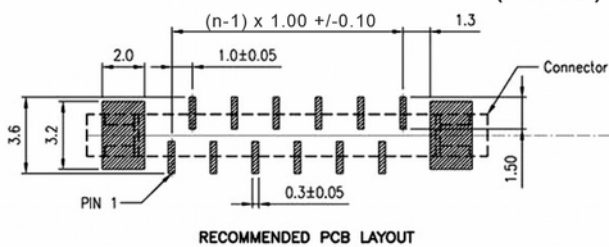
Passende Flex-Kabel:
Compatible Flex Cables:
599



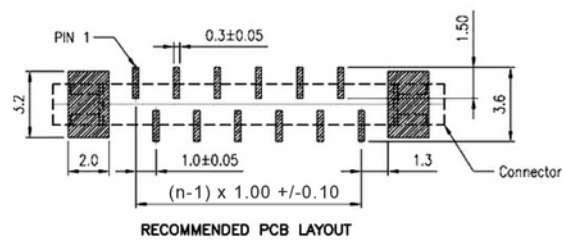
**Layout 1
(Normal)**



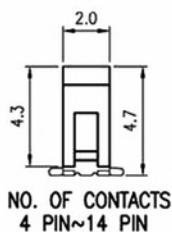
**Layout 2
(Reverse)**



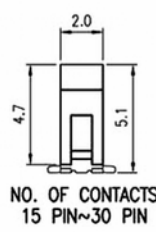
RECOMMENDED PCB LAYOUT



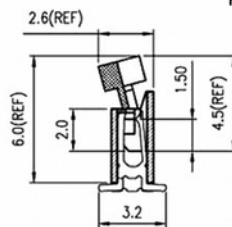
RECOMMENDED PCB LAYOUT



NO. OF CONTACTS
4 PIN~14 PIN



NO. OF CONTACTS
15 PIN~30 PIN



SECTION A-A

Series

5561

Contacts*

20

04-30

Layout*

1

1 Normal
2 Reverse

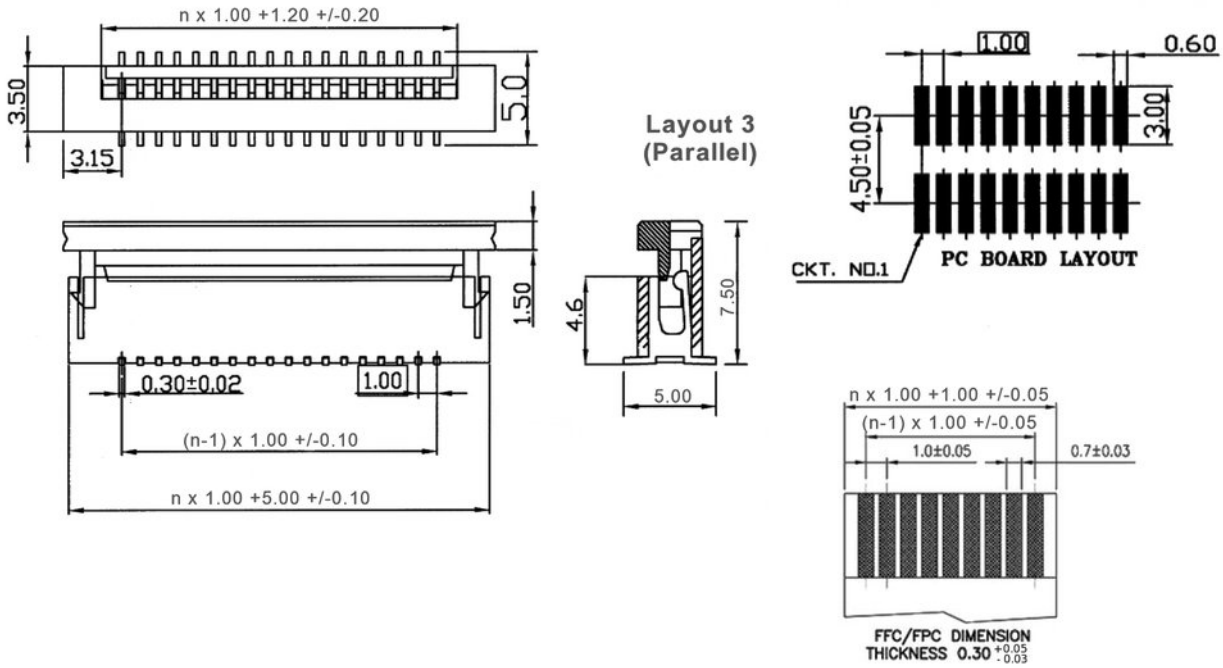
Package

PPTR

PPTR Tape & Reel mit Pick&Place-Pads
Tape & Reel with Pick&PlaceP-Pads

5561

SMT ZIF-Steckverbinder RM 1,00mm, stehend
SMT ZIF-Connectors, 1.00mm Pitch, Vertical



Series

5561

Contacts*

20

04-30

Layout

3

3 Parallel

Packaging*

ST

ST
TR (Option)
PPTR (Option)

* Dies ist ein **Bestellbeispiel** -
bitte durch Ihre Spezifikationen ersetzen.
* This is an **order example** -
please replace by your specifications.

Lieferformen / Packaging Options:

ST In Stangen / In tubes

TR (Option) Tape & Reel / Tape & Reel

PPTR (Option) Tape & Reel mit Pick&Place-Pads / Tape & Reel with Pick&PlaceP-Pads

Reflow-Lötempfehlung

Reflow Soldering Recommendation

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum T_{Smin}	150°C
Temperatur Maximum T_{Smax}	200°C
Dauer $T_{Smin} - T_{Smax}$	60-180s
Temperatur Lötbereich T_L	217°C
Verweildauer oberhalb T_L	60-180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3°C / s
Höchsttemperatur T_P	260°C ±5
Dauer Höchsttemperatur	20-40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6°C / s
Dauer 25°C - Höchsttemperatur T_P	Max. 8 min

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature T_{Smin}	150°C
Maximum Temperatur T_{Smax}	200°C
Duration $T_{Smin} - T_{Smax}$	60-180s
Soldering Range Temperature T_L	217°C
Duration above T_L	60-180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3°C / s
Peak Temperature T_P	260°C ±5
Duration Peak Temperature	20-40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6°C / s
Duration 25°C - Peak Temp. T_P	Max. 8min

